Travel Grant Application ECS Vienna, Austria

The Society's Battery, Corrosion, Dielectric, Electrodesposition, Electronics and Photonics, Energy Technology, High Temperature Materials (HTM), Industrial Electrochemistry and Electrochemical Engineering (IEEE), Organic and Biological Electrochemistry (OBE), Physical and Analytical Electrochemistry, and Sensor Divisions offer travel grants to students presenting papers at the Society's next meeting, in Vienna, Austria, October 4-9, 2009. To apply, complete this application and send it along with a copy of your transcript and a letter from an involved faculty member attesting both to the quality of the student's work and financial needs, and a copy of the student's meeting abstract. For additional information please contact the Division contact below, as requirements might differ between Divisions.

Meeting Site: ______________________________

Name: ______________________________

School Adress: ______________________________

____

Email: ______________________ Phone #: ______________________

Undergraduate Year (U) or Graduate Year (G) - circle one: U3 U4 G1 G2 G3 G4 G5

Major Subject: ______________ Grade point average: __________ out of possible: ________

(please provide a letter of recommendation from your faculty advisor and a copy of your transcript)

Symposium Title (#): ______________________________

____

____

Title of paper to be presented at the meeting: ______________________________

____

____

Are you an ECS Student Member of the Society? ☐ yes ☐ no

(if not, please additionally submit the Awarded Student Membership application)

Estimated meeting expenditures: $ ______________________________

Signature: ______________________ Date: ______________________

Check Division under which award is being applied for: (Applications made to multiple Divisions will be rejected)

☐ Battery-*Send to*: A. Manthiram, Univ. of Texas, ETC 9-104, Austin, TX 78712-0292, USA. E-mail: rmanth@mail.utexas.edu.

☐ Corrosion-*Send to*: N. Missert, Sandia National Labs, MS 1415, P.O. Box 5800, Albuquerque, NM 87185-0100, USA. E-mail: namisse@sandia.gov

☐ Dielectric Science & Technology-*Send to*: H. Rathore, IBM, Internal Mail Stop AE1,B/640, 2070 Rte 52, Hopewell Junction, NY 12533, USA. E-mail: rathore@us.ibm.com

☐ Electrodeposition-*Send to*: Stanko Brankovic, University of Houston, Dept. of ECE, Bldg. 1 N308, Houston, TX 77204, USA. E-mail: stanko.brankovic@mail.uh.edu

☐ Electronics and Photonics-*Send to*: F. Ren, University of Florida, Dept. of Chem. Engr., Gainesville, FL 32611, USA. E-mail: ren@che.ufl.edu

☐ Energy Technology-*Send to*: Matthew Mench, Penn State University, Dept. of Mech. Eng., 327 Reber Bldg., University Park, PA 16802, USA. E-mail: mmench@psu.edu

☐ HTM-*Send to*: Tim Armstrong, Carpenter Technology, Bldg. 68, P.O. Box 14662, Reading, PA 19612, USA. E-mail: tarmstrong@cartec.com

☐ IE&EE-*Send to*: G. Venkat Subramanian, Department of Chemical Engineering, Tennessee Tech University, Cookeville, TN 38505, USA. Email: vsubramanian@tntech.edu

☐ OBE-*Send to*: I. Taniguchi, Kumamoto University, Fac. of Appl. Chem & Biochem., 2-39-1 Kurokami, Kumamoto 860-8555, Japan. E-mail: taniguch@gpo.kumamoto-u.ac.jp

☐ Physical and Analytical Electrochemistry-*Send to*: S. Minteer, Saint louis University, Dept of Chemistry, 221 N Grand Blvd, Saint Louis, MO 63103, USA. E-mail: minteers@slu.edu

☐ Sensor-*Send to*: Y-L. Chang, Nanomix, Inc., 5980 Horton Street, Suite 600, Emeryville, CA 94608, USA. E-mail: ychang@nano.com

Applications for Travel Grants for the Vienna, Austria meeting must be received no later than April 24, 2009.